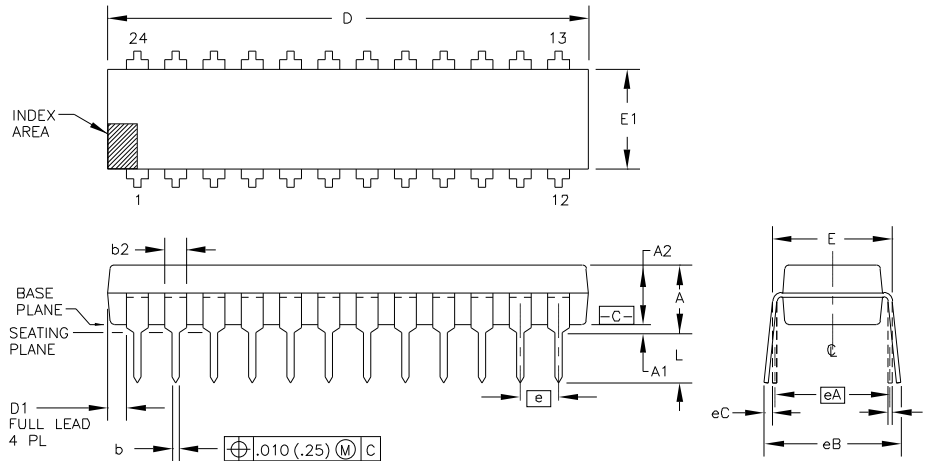


Package Number 243 - 24-Pin Plastic, Single-Wide DIP



DIM	INCHES		MILLIMETERS		N	O	E	DIM	INCHES		MILLIMETERS		N	O	E
	MIN.	MAX.	MIN.	MAX.					MIN.	MAX.	MIN.	MAX.			
A	--	.210	--	5.33	3			L	.115	.150	2.92	3.81	3		
A1	.015	--	0.38	--	3			N	24		24		7		
A2	.115	.195	2.92	4.95											
b	.014	.022	0.36	0.56											
b2	.045	.070	1.14	1.78	9										
c	.008	.014	0.20	0.36											
D	1.230	1.280	31.24	32.51	4										
D1	.005	--	0.13	--	4										
E	.300	.325	7.62	8.26	5										
E1	.240	.280	6.10	7.11	4										
e	.100	BASIC	2.54	BASIC											
eA	.300	BASIC	7.62	BASIC	5										
eB	--	.430	--	10.92	6										
eC	.000	.060	0.00	1.52	6										

NOTES:

- ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
- D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
- E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM  $\overline{C}$ .
- eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- N IS THE MAXIMUM OF TERMINAL POSITIONS.

- POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
- b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
- DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.
- A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
- FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.

PACKAGE NUMBER: Z2243      REV.: D  
 JEDEC NUMBER:      MS-001-AF



PACKAGE DRAWING

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